

1. Introduction

1.1 Testing was performed on the DDR4 DIMM SOCKET TH 288P to determine if it meets the requirement of Product Specification , 108-115124 Rev A

1.2 Scope

This report covers the electrical, mechanical and environmental performance requirements of the DDR4 DIMM SOCKET TH 288P.

1.3 Conclusion

DDR4 DIMM SOCKET TH 288P Type meets the electrical, mechanical and environmental performance requirements of Product Specification, 108-115124 Rev A

1.4 Test Samples

Samples were taken randomly from current production. The following samples were used.

Part Number	Description
2308107-1	DDR4 DIMM SOCKET 0.85mm Pitch TH 288Pos.

Fig. 1

2. Test Contents

NO.	Test Items	Requirements	Judgment
2.1	Examination of Product	Visual, inspection No physical damage.	Acceptable
Electrical Requirements			
2.2	Termination Resistance (Low Level)	Standard Type: 10mΩ Max. ( Initial ) ΔR = 10mΩMax. ( Final )	Acceptable
2.3	Insulation Resistance	Impressed voltage 500V DC for 1 minute. Test between adjacent circuits of unmated connector. 1000MΩ Min.	Acceptable
2.4	Dielectric withstanding Voltage	500 V AC for 1 minute. Test between adjacent circuits of unmated connector. No creeping discharge nor flashover shall occur. Current leakage: 0.5mA Max.	Acceptable
2.5	Current carrying capability / Temperature Rising	30°C Max. (Only 6 contacts) Load with 0.5A	Acceptable

Fig. 2 ( to be continued )

Mechanical Requirements			
2.6	Reseating	No physical damage after 3 times.	Acceptable
2.7	Solderability, lead free	95% coverage. No physical damage; contact gap within manufacturer's tolerance. JESD22-B-102, Condition C, Method 1. Thirty second exposure at 190°C oven. Processing criteria: solder 260±5°C for 5 seconds.	Acceptable
2.8	Vibration (Random)	Vibration Frequency: 5~500 Hz / 1 minute Amplitude:1.52mm Vibration Direction: In each of 3 mutually perpendicular Planes Duration: 2 hours 100mA applied. No electrical discontinuity greater than 1µsec shall occur.	Acceptable
2.9	Mechanical shock	Module thickness:1.40 mm Module weight 45 ± 5 g Profile: Trapezoidal shock of 50 g ± 10%. Velocity change: 170 inches/sec ± 10%. Quantity: Three drops in each of 6 directions are applied to each of the three samples. 100mA applied. No electrical discontinuity greater than 1 µ sec shall occur.	Acceptable
2.10	Durability	Mate and unmate specimens with 1.50 mm thick steel gauge for 25 cycles at a maximum rate of 500 cycles per hour.	Acceptable
2.11	Mating force	Measure force necessary to mate specimens with a 1.50 mm steel gauge at a maximum rate of 5 mm per minute 106.8 N maximum.	Acceptable
2.12	Unmating force (per pin pair)	Axial Tension/Compression machine such as an Instron Tensile Tester. Rate: 12.7 mm/min GS-005 Gauge 14 gf min.	Acceptable

Fig. 2 ( to be continued )



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2.13	Contact backout wipe	Fully seat daisy chain module. Pull module upward until stopped by latches while monitoring for discontinuities. No discontinuities of 1 microsecond or longer duration	Acceptable
2.14	Latch opening force	Measure force necessary to unmate specimens from a 1.50 mm steel gage at a maximum rate of 5 mm per minute. 32.4 N maximum per latch.	Acceptable
2.15	Contact retention	Apply specified load to contact tail and hold for 6 seconds. 3 N minimum per pin. No movement of contact more than 0.38 mm	Acceptable
2.16	Fork lock retention (where applicable)	Apply specified load to fork lock and hold for 6 seconds. 13.3 N minimum per fork lock. Maximum movement of 0.38 mm	Acceptable
2.17	Connector insertion force into PCB	Press socket onto board at a rate of 5 mm per minute. 75 N maximum.	Acceptable
Environmental Requirements			
2.18	Thermal Shock	-55 and 85°C, perform 5 cycles in mated condition.	Acceptable
2.19	Cyclic Temperature & Humidity	Subject mated and mounted specimens to 10 cycles between 25°C at 80% RH and 65°C at 50% RH. Ramp times shall be 0.5 hour with 1 hour dwell time.	Acceptable
2.20	Thermal cycling	Subject mated and mounted specimens to 500 cycles between 15±3°C and 85±3°C as measured on the specimen). Ramps times shall be a minimum of 2°C per minute. Dwell times shall ensure that the contacts reach the temperature extreme (5 minutes minimum). Humidity not controlled.	Acceptable
2.21	Temperature Life	Subject mated and mounted specimens to 105°C for 240 hours.	Acceptable

Fig. 2 ( to be continued )

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2.22	Mixed flowing Gas	<p>EIA-364-65, Class IIA. 30u" Au version (field life 7 years): Five specimens unmated for 160 hours, mated for 80 hours. Five specimens mated for 240 hours. Store module cards at laboratory ambient during the unmated portion of the exposure.</p> <p>15u" Au version (field life 5 years): Five specimens unmated for 112 hours, mated for 56 hours. Five specimens mated for 168 hours. Store module cards at laboratory ambient during the unmated portion of the exposure.</p>	Acceptable
2.23	Thermal Disturbance	<p>Subject mated and mounted specimens to 10 cycles between <math>15\pm 3^{\circ}\text{C}</math> and <math>85\pm 3^{\circ}\text{C}</math> as measured on the part. Ramps shall be a minimum of <math>2^{\circ}\text{C}</math> per minute. Dwell times shall ensure that the contacts reach the temperature extreme (5 minutes minimum). Humidity not controlled.</p>	Acceptable

Fig. 2 ( End )



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### 3. Product Qualification and Requalification Test Sequence

Test or Examination	Test Group (a)									
	1	2	3	4	5	6	7	8	9	10
	Test Sequence (b)									
Initial examination of product	1	1	1	1	1	1	1	1	1	1
Low level contact resistance	2,6,8	2,7,9,13	2,4,6,8,10	2,5,7,9,11						2,5,7,9
Insulation resistance		3,10								
Withstanding voltage		4,11								
Current carrying capacity									2	
Reseating	7	12		10						8
Solderability						2				
Vibration, random			7							
Mechanical shock			9							
Durability	4(c)	5(c)	3(c)	3(c)						3(c)
Mating force					2					
Unmating force per pin pair								3		
Latch opening force					3					
Contact retention								3		
Fork lock retention								2		
Connector insertion force into PCB								2		
Contact backout wipe	3									
Thermal shock		6								
Cyclic temperature & humidity		8								
Thermal cycling										6
Temperature life	5		5(d)	4(d)						4(d)
Mixed flowing gas				6						
Thermal disturbance				8						
Final examination of product	9	14	11	12	4	3	4	4	3	10

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**NOTE**

- (a) See paragraph 4.1.A.*
- (b) Numbers indicate sequence in which tests are performed.*
- (c) Durability preconditioning with only 5 cycles.*
- (d) Temperature life preconditioning, 120 hours duration.*

Figure 3

4. TEST RESULT

4.1 TEST RESULT For Standard Type

Condition	Measure Item	N	Unit	Results			Requirement	Judgment
				MAX.	MIN.	AVE.		
Test Group 1								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
	Termination Resistance	1440	mΩ	8.69mΩ	4.52mΩ	6.56mΩ	10mΩMAX.	Acceptable
After Durability	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
After Contact backout wipe	Circuit Continuity	5	μS	No discontinuity			1μsec. MIN.	Acceptable
After Temperature life	ΔR	1440	mΩ	5.30mΩ	0.01mΩ	2.04mΩ	10mΩMAX.	Acceptable
After Reseating	ΔR	1440	mΩ	5.49mΩ	0mΩ	1.98mΩ	10mΩMAX.	Acceptable
Final	Appearance	5	-	No abnormalities			No abnormalities	Acceptable

Fig. 4 ( to be continued )

Condition	Measure Item	N	Unit	Results			Requirement	Judgment
				MAX.	MIN.	AVE.		
Test Group 2								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
	Termination Resistance	1440	mΩ	9.28mΩ	4.51mΩ	7.16mΩ	10mΩMAX.	Acceptable
	Insulation resistance	5	-	1.14 x 10 <sup>12</sup> Ω MIN.			1000MΩMIN	Acceptable
	Withstanding voltage	5	-	No creeping discharge nor flashover occurred.			No abnormalities	Acceptable
After Durability	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
After Thermal shock	ΔR	1440	mΩ	4.43mΩ	0mΩ	1.62mΩ	10mΩMAX.	Acceptable
After Cyclic temperature & humidity	ΔR	1440	mΩ	4.89mΩ	0mΩ	1.70mΩ	10mΩMAX.	Acceptable
	Insulation resistance	5	-	1 x 10 <sup>12</sup> Ω MIN.			1000MΩMIN	Acceptable
	Withstanding voltage	5	-	No creeping discharge nor flashover occurred.			No abnormalities	Acceptable
After Reseating	ΔR	1440	mΩ	5.21 mΩ	0.05mΩ	1.71 mΩ	10mΩMAX.	Acceptable
Final	Appearance	5	-	No abnormalities			No abnormalities	Acceptable

Fig. 4 ( to be continued )

Condition	Measure Item	N	Unit	Results			Requirement	Judgment
				MAX.	MIN.	AVE.		
Test Group 3								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
	Termination Resistance	1440	mΩ	8.70mΩ	4.54mΩ	6.63mΩ	10mΩMAX.	Acceptable
After Durability	ΔR	1440	mΩ	5.42mΩ	0.02mΩ	1.98mΩ	10mΩMAX.	Acceptable
After Temperature life	ΔR	1440	mΩ	5.38mΩ	0.05mΩ	1.09mΩ	10mΩMAX.	Acceptable
Vibration (Random) During test	Circuit Continuity	5	μS	No discontinuity			1μsec. MIN.	Acceptable
After Vibration	ΔR	1440	mΩ	4.25mΩ	0.01mΩ	1.55mΩ	10mΩMAX.	Acceptable
Mechanical Shock During test	Circuit Continuity	5	μS	No discontinuity			1μsec. MIN.	Acceptable
After Mechanical Shock	ΔR	1440	mΩ	4.43mΩ	0mΩ	1.56mΩ	10mΩMAX.	Acceptable
Final	Appearance	5	-	No abnormalities			Final	Appearance

Fig. 4 ( to be continued )



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Condition	Measure Item	N	Unit	Results			Requirement	Judgment
				MAX.	MIN.	AVE.		
Test Group 4								
Initial	Appearance	10	-	No abnormalities			No abnormalities	Acceptable
	Termination Resistance	2880	mΩ	9.18mΩ	4.53mΩ	6.86mΩ	10mΩMAX.	Acceptable
After Durability	Appearance	10	-	No abnormalities			No abnormalities	Acceptable
After Temperature life	ΔR	2880	mΩ	4.59mΩ	0.01mΩ	1.61mΩ	10mΩMAX.	Acceptable
After MFG	ΔR	2880	mΩ	5.62mΩ	0mΩ	1.90mΩ	10mΩMAX.	Acceptable
After Thermal Disturbance	ΔR	2880	mΩ	5.15mΩ	0.01mΩ	1.84mΩ	10mΩMAX.	Acceptable
After Reseating	ΔR	2880	mΩ	5.31mΩ	0.01mΩ	1.84mΩ	10mΩMAX.	Acceptable
Final	Appearance	10	-	No abnormalities			Final	Appearance

Fig. 4 ( to be continued )

Condition	Measure Item	N	Unit	Results			Requirement	Judgment
				MAX.	MIN.	AVE.		
Test Group 5								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
Mating force	Mating force	5	N	77.40N	64.60N	72.60N	106.8N MAX.	Acceptable
Latch opening force	Latch opening force	5	N	7.34N	6.31N	6.84N	32.4N MAX.	Acceptable
Final	Appearance	5	-	No abnormalities			Final	Appearance
Test Group 6								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
Solderability	Appearance	5	-	More than 95% of tested area was covered with fresh, wet solder			95% MIN.	Acceptable
Final	Appearance	5	-	No abnormalities			Final	Appearance
Test Group 7								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
Fork lock retention	Fork lock retention	5	N	13.3N MIN			13.3N MIN	Acceptable
Contact retention	Contact retention	5	N	3N MIN			3N MIN	Acceptable
Final	Appearance	5	-	No abnormalities			Final	Appearance

Fig. 4 ( to be continued )



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Condition	Measure Item	N	Unit	Results			Requirement	Judgment
				MAX.	MIN.	AVE.		

Test Group 8								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
Connector insertion force into PCB	Connector insertion force into PCB	5	N	19.80N	15.80N	17.54N	75N MAX.	Acceptable
Unmating force per pin pair	Unmating force per pin pair	5	g	21.48 g	17.77 g	19.86 g	14g MIN.	Acceptable
Final	Appearance	5	-	No abnormalities			Final	Appearance

Test Group 9								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
Current carrying capacity.	Current carrying capacity.	5	°C	3.60°C	3.00°C	3.36°C	30°C MAX.	Acceptable
Final	Appearance	5	-	No abnormalities			Final	Appearance

Condition	Measure Item	N	Unit	Results			Requirement	Judgment
				MAX.	MIN.	AVE.		
Test Group 10								
Initial	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
	Termination Resistance	1440	mΩ	8.72mΩ	4.50mΩ	6.10mΩ	10mΩMAX.	Acceptable
After Durability	Appearance	5	-	No abnormalities			No abnormalities	Acceptable
After Temperature life	ΔR	1440	mΩ	5.21mΩ	0.04mΩ	1.90mΩ	10mΩMAX.	Acceptable
After Thermal cycling	ΔR	1440	mΩ	9.78mΩ	-2.00mΩ	1.98mΩ	10mΩMAX.	Acceptable
After Reseating	ΔR	1440	mΩ	5.50mΩ	0.03mΩ	1.20mΩ	10mΩMAX.	Acceptable
Final	Appearance	5	-	No abnormalities			Final	Appearance

Fig. 4 ( END )